

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT3489933

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAKAYUKI TANI	06/18/1998
TAKASHI SEKIBATA	06/18/1998
HARUO HYODO	06/18/1998
RECEIVING PARTY DATA	
Name:	SANYO ELECTRIC CO., LTD.
Street Address:	5-5, KEIHAN-HONDORI 2-CHOME
City:	MORIGUCHI CITY, OSAKA
State/Country:	JAPAN
PROPERTY NUMBERS Total: 2	
Property Type	Number
Application Number:	09543861
Application Number:	10136368
CORRESPONDENCE DATA	
Fax Number:	(602)244-3169
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	602-244-6648
Email:	patents@onsemi.com
Correspondent Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
Address Line 1:	5005 E. MCDOWELL ROAD
Address Line 2:	MD A700
Address Line 4:	PHOENIX, ARIZONA 85008
ATTORNEY DOCKET NUMBER:	199700964D02 AND D03
NAME OF SUBMITTER:	KELLY A. NELSON
SIGNATURE:	/Kelly A.Nelson/
DATE SIGNED:	08/19/2015
Total Attachments: 2	
source=199700964_assignment (F0980088US00)#page1.tif	
source=199700964_assignment (F0980088US00)#page2.tif	

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) and other good and valuable consideration paid to each of the undersigned

Takayuki TANI, Takashi SEKIBATA and Haruo HYODO

Insert Name(s)
of Inventor(s)

the undersigned hereby sell(s) and assign(s) to

Insert Name(s)
of Assignee(s)

SANYO ELECTRIC CO., LTD.

Address

of 5-5, Keihan-Hondori 2-chome, Moriguchi City, Osaka, Japan

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Title of
Invention

SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING SAME

Date of Signing
of Application

for which an application for patent in the United States has been executed by the undersigned on

June 18, 1998

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

The undersigned hereby grant(s) the firm of WENDEROTH, LIND & PONACK, L.L.P., 2033 K Street, N.W., Suite 800, Washington, DC 20006, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the Rule of the United States Patent Office for recordation of this document.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

Date June 18, 1998 Name of Inventor 谷 孝行 Takayuki ITANI
Date June 18, 1998 Name of Inventor 関 端 隆 Takashi SEKIBATA
Date June 18, 1998 Name of Inventor 兵藤 治 雄 Haruo HYODO
Date _____ Name of Inventor _____
Date _____ Name of Inventor _____
Date _____ Name of Inventor _____

(This assignment should preferably be acknowledged before a United States Consul. If not, then the execution by the Inventor(s) should be witnessed by at least two witnesses who sign here.)

Witness 石川 忠 弘
Witness Chifuyu Onodera

ACKNOWLEDGEMENT

_____ } ss
_____ }

This _____ day of _____, 19_____, before me
personally came the above-named _____

to me personally known as the individual(s) who executed the foregoing assignment, who did acknowledge to me that he (they) executed the same of his (their) own free will for the purposes therein set forth.

SEAL

Official Signature

Official Title

The above application may be more particularly identified as follows:

U.S. Application Serial No. 09/036,783 Filing Date March 9, 1998
Applicant Reference Number GSY643-US Atty Docket No. 1213/GSY643-US
Title of Invention SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING SAME